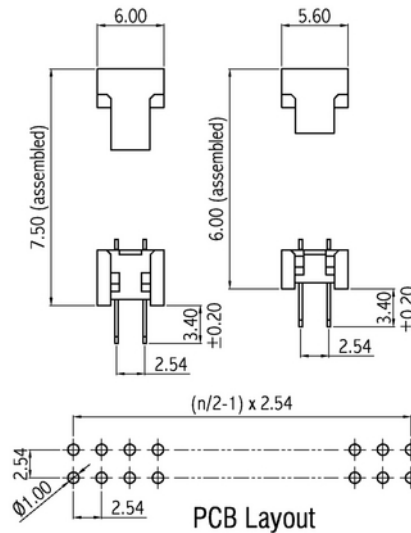
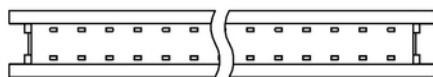
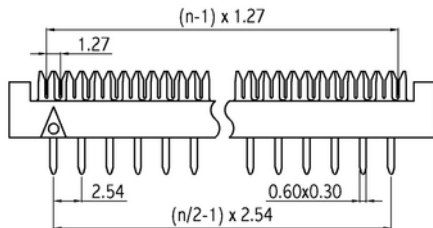
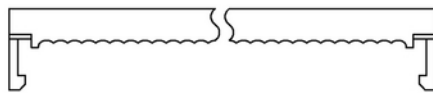
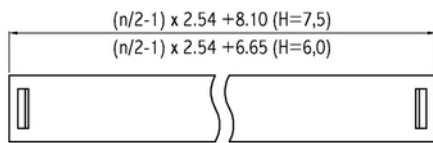
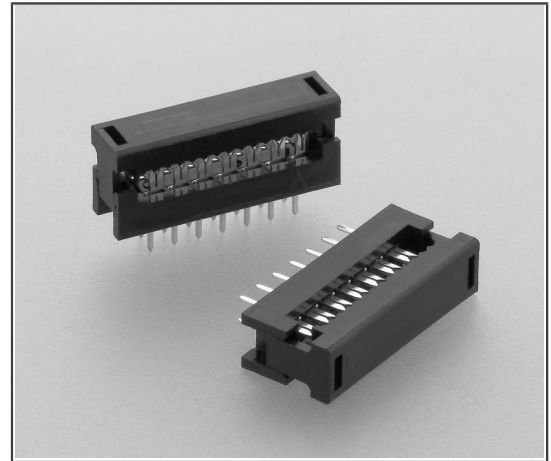


IDC Leiterplattenverbinder RM 2,54mm – Bauhöhen 7,5 / 6,0mm

IDC Printed Circuit Connectors, 2.54mm Pitch – 7.5mm / 6.0mm Profiles

Technische Daten / Technical Data

Isolierkörper	Thermoplast, nach UL94 V-0
<i>Insulator</i>	<i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial	Kupferlegierung
<i>Contact Material</i>	<i>Copper alloy</i>
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm)
<i>Contact Surface</i>	<i>Acc. to options (see below), over Ni (1.3 ... 2.5µm)</i>
Durchgangswiderstand	< 20 mΩ
<i>Contact Resistance</i>	< 20 mΩ
Isolationswiderstand	> 1000 MΩ
<i>Insulation Resistance</i>	> 1000 MΩ
Spannungsfestigkeit	500 V AC
<i>Test Voltage</i>	<i>500 V AC</i>
Nennstrom	1 A
<i>Current Rating</i>	<i>1 A</i>
Temperaturbereich	-40 °C ... +105 °C
<i>Temperature Range</i>	<i>-40 °C ... +105 °C</i>
Verarbeitung	Wellenlötverfahren
<i>Processing</i>	<i>Wave soldering</i>



Series	Contacts*	Plating*	Height*	Colour (Optional)
TC-02800	64	60	7,5	..
	08 10 14 16 18 20 22 24 26 28 30 34 40 50 60 64	50 Verzinkt (Standard) Tin plated (Standard) 60 Sel. Au/Sn (Standard) Duplex Plating (Standard) 00 Vergoldet (auf Anfrage) Gold plated (on request)	7,5 H=7,50 B=6,00mm 6 H=6,00 B=5,60mm	[] Standard: Schwarz Standard: Black 6 Grau Grey

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
 * This is an **order example** - please replace by your specifications.

Empfehlungen für das Wellenlötverfahren

Recommendations for Wave Soldering

Die Bauteile sollten bei einer Lötbadtemperatur von 260°C in max. 5 Sekunden verlötet werden.
Items should be soldered at a solder temperature of 260°C in 5 seconds max.

Empfohlenes Wellenlötprofil:
Recommended wave soldering profile:

